Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4237	(29/830,831,825,835,846-847,852). CCLS.	USPAT; USOCR	OR	OFF	2005/12/13 10:56
S2	2090244	S1 and (etch or etching or etched) oand (plate or plating or plated)	USPAT; USOCR	OR	ON	2005/12/13 10:56
S3	1549	S1 and (etch or etching or etched) and (plate or plating or plated)	USPAT; USOCR	OR	ON	2005/12/14 09:56
S4	859	S1 and (etch or etching or etched) and (plate or plating or plated)and solder	USPAT; USOCR	OR	ON	2005/12/14 09:56
S5	859	S1 and (etch or etching or etched) and (plate or plating or plated) and · solder	USPAT; USOCR	OR	ON	2005/12/13 12:35
S7	662	S1 and (etch or etching or etched) and (plating) and solder	USPAT; USOCR	OR	ON	2005/12/13 12:37
S8	662	S1 and (etch or etching or etched) and (plating) and solder	USPAT; USOCR	OR	ON	2005/12/13 14:21
S9	3841	(438/618,622,629,638,642,745). CCLS.	USPAT; USOCR	OR	OFF	2005/12/14 13:44
S10	3841	S9	USPAT; USOCR	OR	ON	2005/12/13 14:23
S11	266	S9 and solder	USPAT; USOCR	OR	ON	2005/12/13 14:24
S12	4237	(29/830,831,825,835,846-847,852). CCLS.	USPAT; USOCR	OR	OFF	2005/12/14 09:11
S13	759	S12 and (etch or etching or etched) and (plating or plated) and solder	USPAT; USOCR	OR	ON	2005/12/14 09:11
S14	0	S12 same (etch or etching or etched) and (plate or plating or plated or $plating or $plated)	USPAT; USOCR	OR	ON	2005/12/14 09:59
S15	0	S12 same (etch or etching or etched) and (plate or plating or plated)	USPAT; USOCR	OR	ON	2005/12/14 09:59
S16	0	(S12 same (etch or etching or etched)) and (plate or plating or plated)	USPAT; USOCR	OR	ON	2005/12/14 10:00
S17	1549	(S12 and (etch or etching or etched)) and (plate or plating or plated)	USPAT; USOCR	OR	ON	2005/12/14 10:00
S18	0	(S12 same (plate or plating or plated))	USPAT; USOCR	OR	ON	2005/12/14 10:00
S19	1048	(S12 and ((plate or plating or plated) same ((etch or etching or etched))))	USPAT; USOCR	OR	ON	2005/12/14 10:01

S20	1048	S12 and ((plate or plating or plated) same ((etch or etching or etched)))	USPAT; USOCR	OR	ON	2005/12/14 10:01
S21	872	S12 and ((plating or plated) same ((etch or etching or etched)))	USPAT; USOCR	OR	ON	2005/12/14 10:02
S22	533	S12 and ((plating or plated) same ((etch or etching or etched))) and solder	USPAT; USOCR	OR	ON	2005/12/14 10:02
S23	5096	sacrificial adj layer	USPAT; USOCR	OR	ON	2005/12/14 13:44
S24	4501	sacrificial adj layer and (etching or etched)	USPAT; USOCR	OR	ON	2005/12/14 13:45
S25	728	sacrificial adj layer and (etching or etched) and (plating or plated)	USPAT; USOCR	OR	ON	2005/12/14 13:45
S26	242	sacrificial adj layer and (etching or etched) and (plating or plated) and solder	USPAT; USOCR	OR	ON	2005/12/14 13:46
S27	53	sacrificial adj layer and (etching or etched) with (plating or plated) and solder	USPAT; USOCR	OR	ON	2005/12/15 07:21
S28	1	"5245751".pn.	USPAT; USOCR	OR	ON	2005/12/15 07:21
S29	0	(mutsukawa).in.	USPAT; USOCR	OR	ON	2005/12/15 08:30
S30	896	(etching) and (plating or electroplating) and solder	EPO; JPO; DERWENT	OR	ON	2005/12/15 08:31
S31	724	(etching) and (plating or electroplating) and solder and @pd<"20020917"	EPO; JPO; DERWENT	OR	ON	2005/12/15 08:32
S32	470	(etching) and (plating or electroplating) and solder and @pd<"20020917" and (Ni or nickel or Cu or copper)	EPO; JPO; DERWENT	OR	ON	2005/12/15 08:33
S33	578	(etching) and (plating or electroplating) and solder and @pd<"20020917" and (Ni or nickel or Cu or copper or Co or cobalt)	EPO; JPO; DERWENT	OR	ON	2005/12/15 08:33
S34	471	(etching) and (plating or electroplating) and solder and @pd<"20020917" and (Ni or nickel or Cu or copper or cobalt)	EPO; JPO; DERWENT	OR	ON	2005/12/15 08:33